

P-Channel 20-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, cellular and cordless telephones.

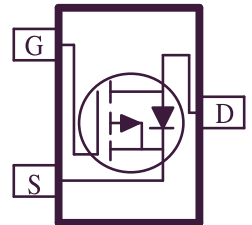
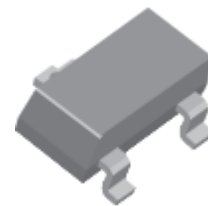
- Low $r_{DS(on)}$ provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe SOT-23 saves board space
- Fast switching speed
- High performance trench technology

PRODUCT SUMMARY

V_{DS} (V)	$r_{DS(on)}$ (OHM)	I_D (A)
-20	0.026 @ $V_{GS} = -4.5V$	-5.7
	0.035 @ $V_{GS} = -2.5V$	-4.9



RoHS
COMPLIANT
HALOGEN
FREE



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ C$ UNLESS OTHERWISE NOTED)

Parameter		Symbol	Ratings	Units
Drain-Source Voltage		V_{DS}	-20	V
Gate-Source Voltage		V_{GS}	± 8	
Continuous Drain Current ^a	$T_A = 25^\circ C$	I_D	-5.7	A
	$T_A = 70^\circ C$		-4.7	
Pulsed Drain Current ^b		I_{DM}	-10	
Power Dissipation ^a	$T_A = 25^\circ C$	P_D	1.25	W
	$T_A = 70^\circ C$		0.8	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 150	$^\circ C$

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Maximum	Units
Maximum Junction-to-Ambient ^a	$t \leq 5$ sec	R_{THJA}	100	$^\circ C/W$
	Steady-State		150	

Notes

- Surface Mounted on 1" x 1" FR4 Board.
- Pulse width limited by maximum junction temperature

SPECIFICATIONS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ	Max	
Static						
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 uA	-0.3			
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±8 V			±10	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -16 V, V _{GS} = 0 V			-1	μA
		V _{DS} = -16 V, V _{GS} = 0 V, T _J = 55°C			-10	
On-State Drain Current ^A	I _{D(on)}	V _{DS} = -5 V, V _{GS} = -4.5 V	-10			A
Drain-Source On-Resistance ^A	r _{DS(on)}	V _{GS} = -4.5 V, I _D = -1 A			26	mΩ
		V _{GS} = -2.5 V, I _D = -1 A			35	
Forward Tranconductance ^A	g _{fs}	V _{DS} = -5 V, I _D = -1 A		12		S
Diode Forward Voltage	V _{SD}	I _S = -0.46 A, V _{GS} = 0 V		-0.6		V
Dynamic ^b						
Total Gate Charge	Q _g	V _{DS} = -5 V, V _{GS} = -4.5 V, I _D = -1 A		10		nC
Gate-Source Charge	Q _{gs}			2		
Gate-Drain Charge	Q _{gd}			3		
Turn-On Delay Time	t _{d(on)}	V _{DD} = -10 V, I _L = -1 A, V _{GEN} = -4.5 V, R _G = 6 Ω		10		ns
Rise Time	t _r			10		
Turn-Off Delay Time	t _{d(off)}			30		
Fall-Time	t _f			20		

Notes

- Pulse test: $PW \leq 300 \mu\text{s}$ duty cycle $\leq 2\%$.
- Guaranteed by design, not subject to production testing.